

FQD10N20C / FQU10N20C

N-Channel QFET® MOSFET

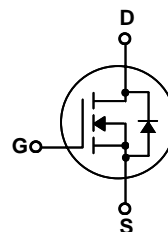
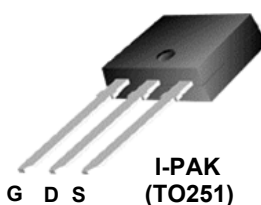
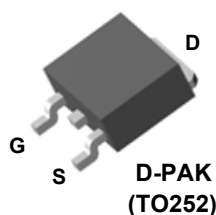
200 V, 7.8 A, 360 mΩ

Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor®'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 7.8 A, 200 V, $R_{DS(on)} = 360 \text{ m}\Omega$ (Max.)@ $V_{GS} = 10 \text{ V}$, $I_D = 3.9 \text{ A}$
- Low Gate Charge (Typ. 20 nC)
- Low C_{rss} (Typ. 40.5 pF)
- 100% Avalanche Tested



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | FQD10N20C / FQU10N20C | Unit |
|----------------|---|-----------------------|---------------------|
| V_{DSS} | Drain-Source Voltage | 200 | V |
| I_D | Drain Current - Continuous ($T_C = 25^\circ\text{C}$) | 7.8 | A |
| | - Continuous ($T_C = 100^\circ\text{C}$) | 5.0 | A |
| I_{DM} | Drain Current - Pulsed (Note 1) | 31.2 | A |
| V_{GSS} | Gate-Source Voltage | ± 30 | V |
| E_{AS} | Single Pulsed Avalanche Energy (Note 2) | 210 | mJ |
| I_{AR} | Avalanche Current (Note 1) | 7.8 | A |
| E_{AR} | Repetitive Avalanche Energy (Note 1) | 5.0 | mJ |
| dv/dt | Peak Diode Recovery dv/dt (Note 3) | 5.5 | V/ns |
| P_D | Power Dissipation ($T_C = 25^\circ\text{C}$) | 50 | W |
| | - Derate above 25°C | 0.4 | W/ $^\circ\text{C}$ |
| T_J, T_{STG} | Operating and Storage Temperature Range | -55 to +150 | $^\circ\text{C}$ |
| T_L | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | 300 | $^\circ\text{C}$ |

Thermal Characteristics

| Symbol | Parameter | FQD10N20C / FQU10N20C | Unit |
|-----------------|---|-----------------------|---------------------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case, Max. | 2.5 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient* | 50 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient, Max. | 110 | $^\circ\text{C}/\text{W}$ |

* When mounted on the minimum pad size recommended (PCB Mount)

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Unit |
|--------|-----------|-----------------|-----|-----|-----|------|
|--------|-----------|-----------------|-----|-----|-----|------|

Off Characteristics

| | | | | | | |
|--------------------------------|---|---|-----|------|------|---------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ | 200 | -- | -- | V |
| $\Delta BV_{DSS} / \Delta T_J$ | Breakdown Voltage Temperature Coefficient | $I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C | -- | 0.28 | -- | V/ $^\circ\text{C}$ |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 200\text{ V}, V_{GS} = 0\text{ V}$ | -- | -- | 10 | μA |
| | | $V_{DS} = 160\text{ V}, T_C = 125^\circ\text{C}$ | -- | -- | 100 | μA |
| I_{GSSF} | Gate-Body Leakage Current, Forward | $V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$ | -- | -- | 100 | nA |
| I_{GSSR} | Gate-Body Leakage Current, Reverse | $V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$ | -- | -- | -100 | nA |

On Characteristics

| | | | | | | |
|--------------|-----------------------------------|---|-----|------|------|----------|
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ | 2.0 | -- | 4.0 | V |
| $R_{DS(on)}$ | Static Drain-Source On-Resistance | $V_{GS} = 10\text{ V}, I_D = 3.9\text{ A}$ | -- | 0.29 | 0.36 | Ω |
| g_{FS} | Forward Transconductance | $V_{DS} = 40\text{ V}, I_D = 3.9\text{ A}$ | -- | 5.6 | -- | S |

Dynamic Characteristics

| | | | | | | |
|-----------|------------------------------|--|----|------|-----|----|
| C_{iss} | Input Capacitance | $V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$ | -- | 395 | 510 | pF |
| C_{oss} | Output Capacitance | | -- | 97 | 125 | pF |
| C_{rss} | Reverse Transfer Capacitance | | -- | 40.5 | 53 | pF |

Switching Characteristics

| | | | | | | |
|--------------|---------------------|--|----|------|-----|----|
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DD} = 100\text{ V}, I_D = 9.5\text{ A},$ $R_G = 25\text{ }\Omega$ | -- | 11 | 30 | ns |
| t_r | Turn-On Rise Time | | -- | 92 | 190 | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | -- | 70 | 150 | ns |
| t_f | Turn-Off Fall Time | | -- | 72 | 160 | ns |
| Q_g | Total Gate Charge | $V_{DS} = 160\text{ V}, I_D = 9.5\text{ A},$ $V_{GS} = 10\text{ V}$ | -- | 20 | 26 | nC |
| Q_{gs} | Gate-Source Charge | | -- | 3.1 | -- | nC |
| Q_{gd} | Gate-Drain Charge | | -- | 10.5 | -- | nC |

Drain-Source Diode Characteristics and Maximum Ratings

| | | | | | | |
|-----------------|---|---|----|------|------|----|
| I _S | Maximum Continuous Drain-Source Diode Forward Current | | -- | -- | 7.8 | A |
| I _{SM} | Maximum Pulsed Drain-Source Diode Forward Current | | -- | -- | 31.2 | A |
| V _{SD} | Drain-Source Diode Forward Voltage | V _{GS} = 0 V, I _S = 7.8 A | -- | -- | 1.5 | V |
| t _{rr} | Reverse Recovery Time | V _{GS} = 0 V, I _S = 9.5 A, dI _F / dt = 100 A/μs | -- | 158 | -- | ns |
| Q _{rr} | Reverse Recovery Charge | | -- | 0.97 | -- | μC |

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 5.2\text{ mH}$, $I_{AS} = 7.8\text{ A}$, $V_{DD} = 50\text{ V}$, $R_G = 25\text{ }\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 9.5\text{ A}$, $di/dt \leq 300\text{ A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Essentially independent of operating temperature

Typical Characteristics

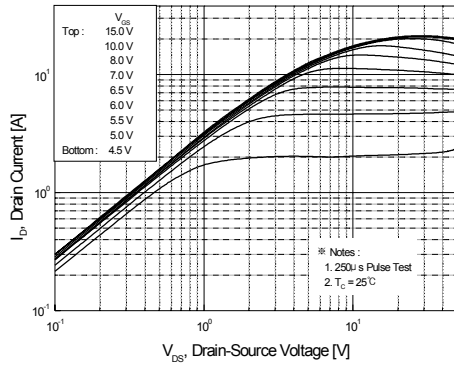


Figure 1. On-Region Characteristics

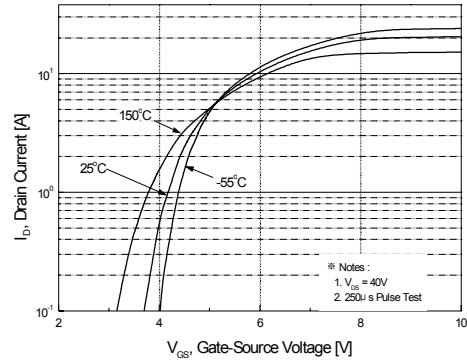


Figure 2. Transfer Characteristics

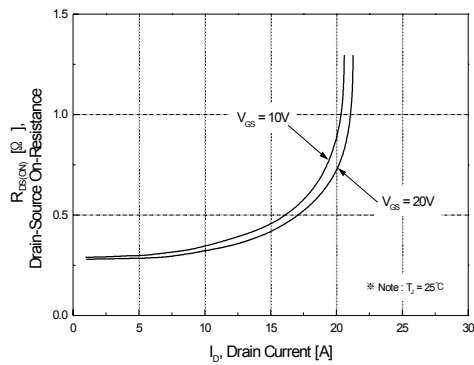


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

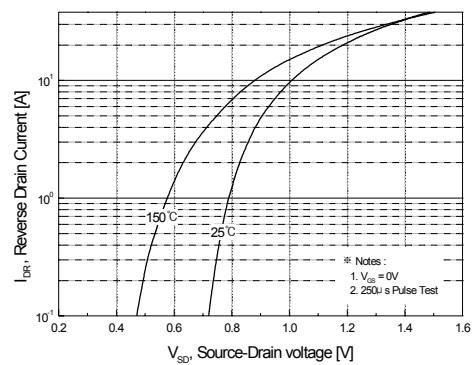


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

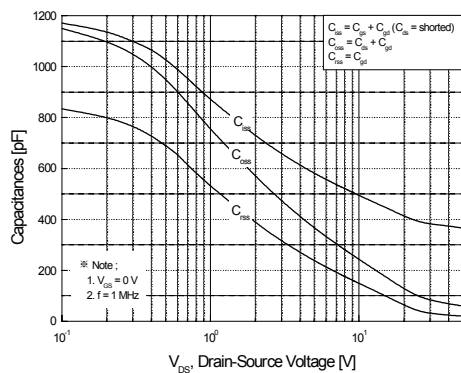


Figure 5. Capacitance Characteristics

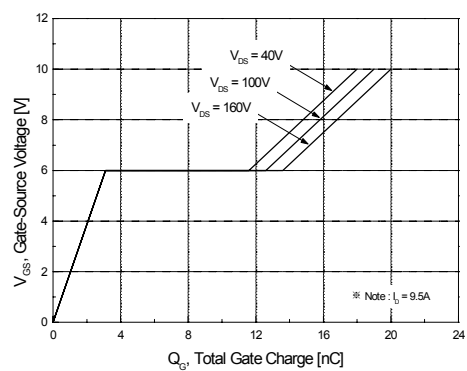


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

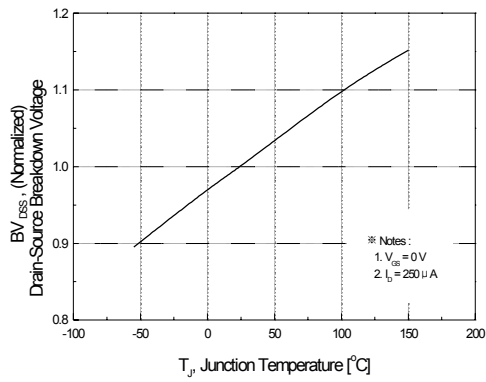


Figure 7. Breakdown Voltage Variation vs Temperature

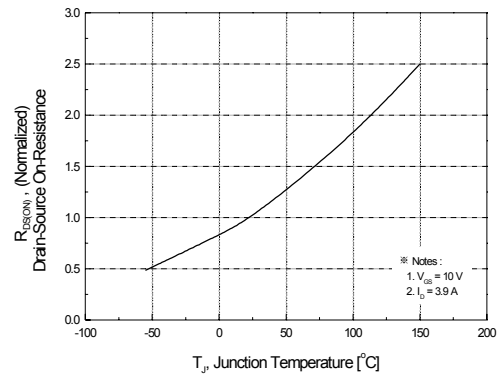


Figure 8. On-Resistance Variation vs Temperature

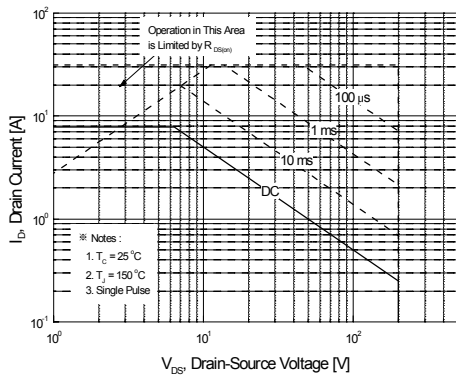


Figure 9. Maximum Safe Operating Area

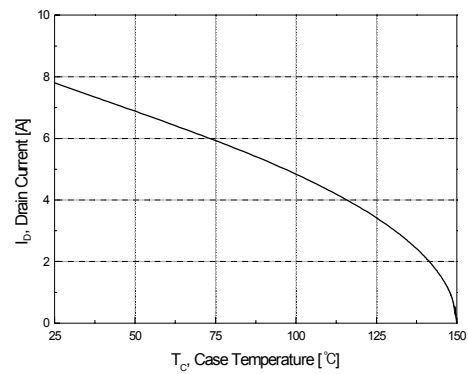


Figure 10. Maximum Drain Current vs Case Temperature

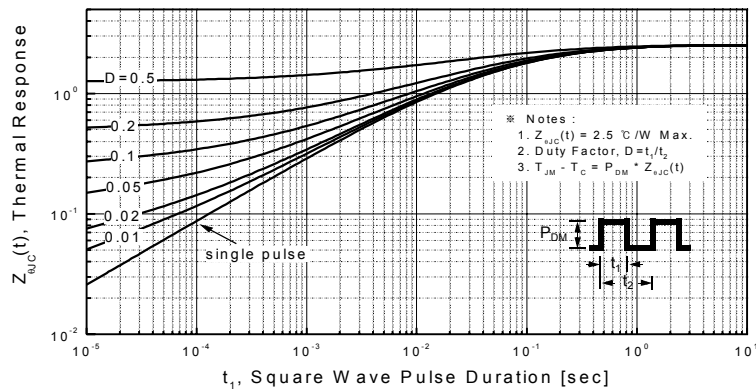
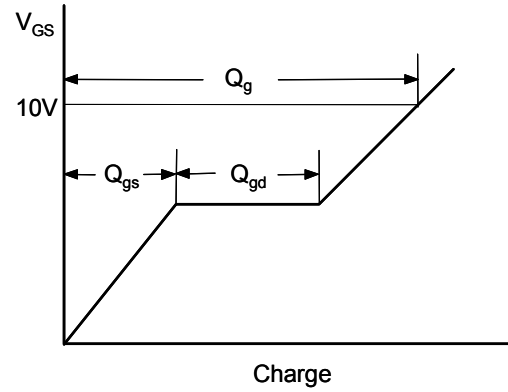
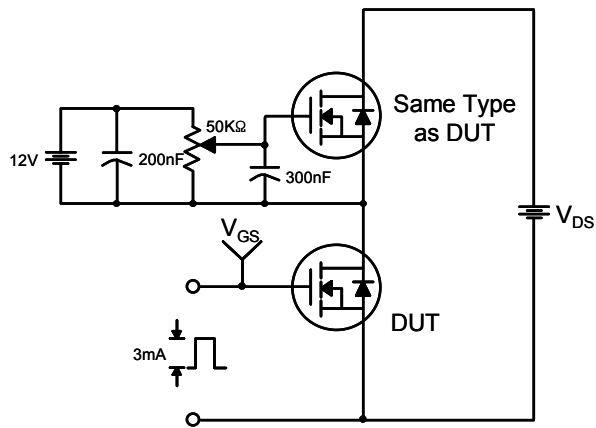
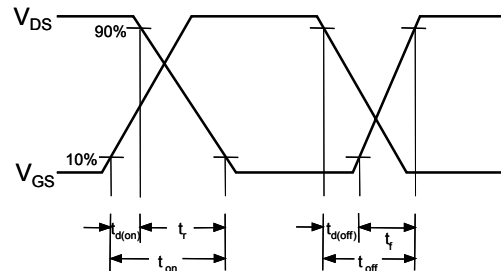
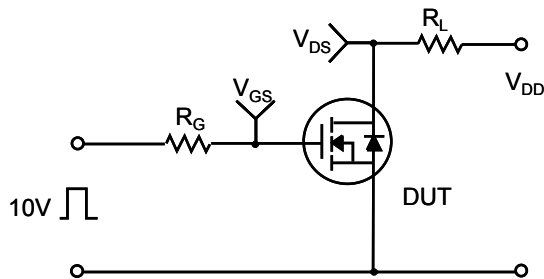


Figure 11. Transient Thermal Response Curve

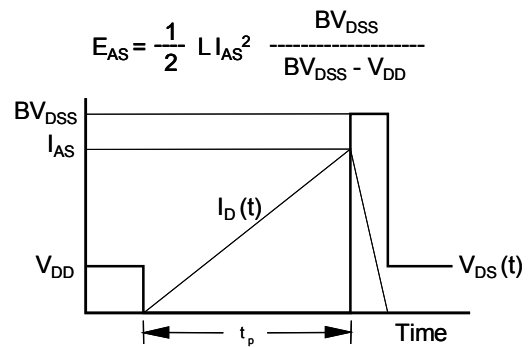
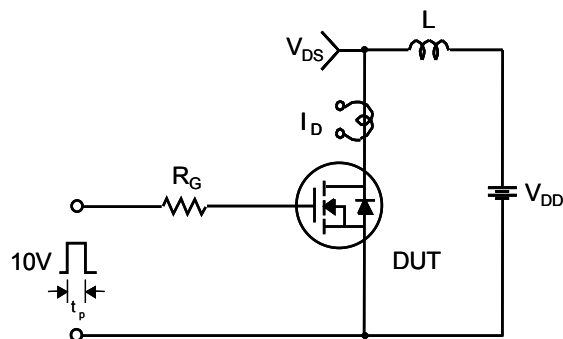
Gate Charge Test Circuit & Waveform



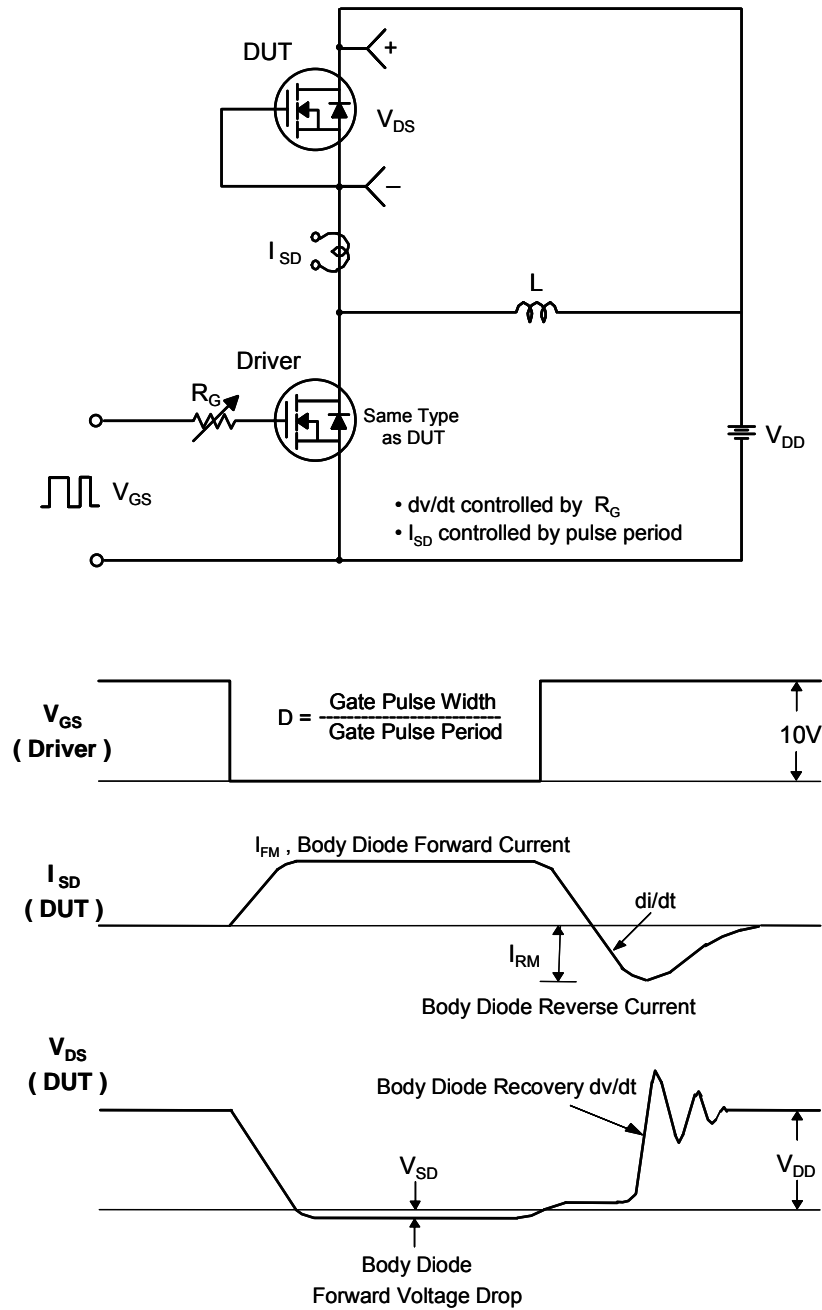
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

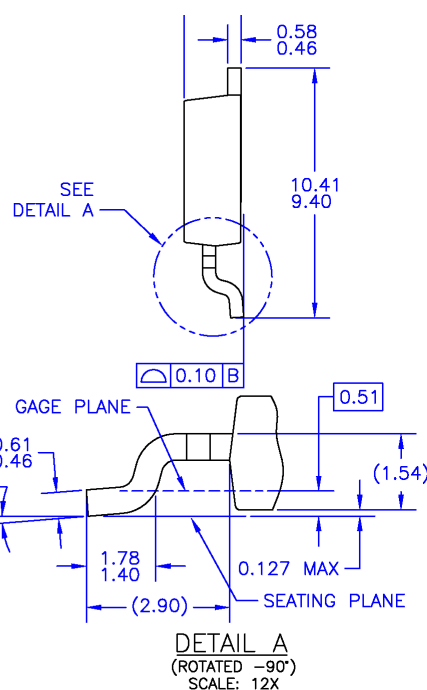
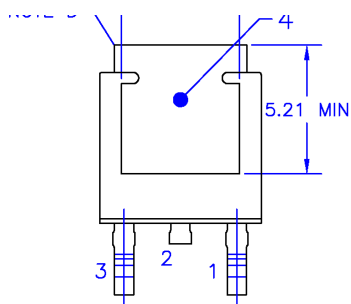
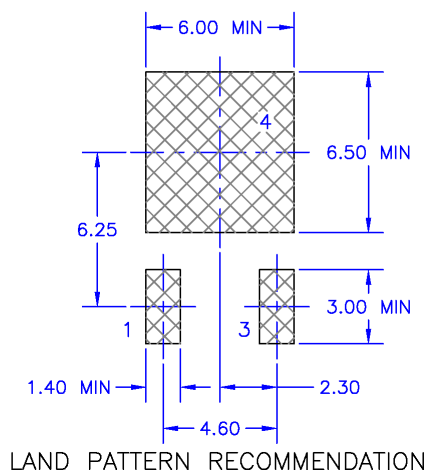
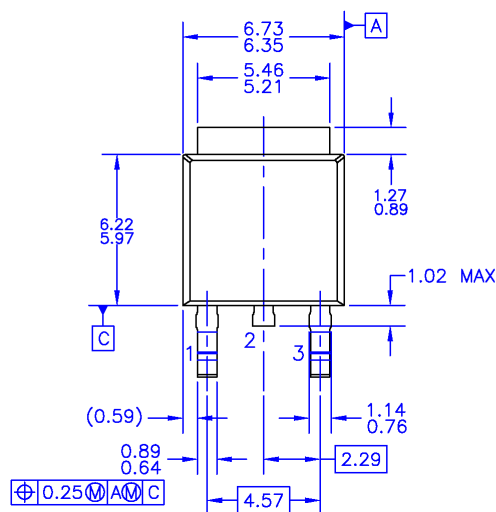


Peak Diode Recovery dv/dt Test Circuit & Waveforms



Mechanical Dimensions

D-PAK



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE C, VARIATION AA.
 - B) ALL DIMENSIONS ARE IN MILLIMETERS.
 - C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION.
 - E) PRESENCE OF TRIMMED CENTER LEAD IS OPTIONAL.
 - F) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
 - G) LAND PATTERN RECOMMENDATION IS BASED ON IPC7351A STD TO220P1003X238-3N.
 - H) DRAWING NUMBER AND REVISION: MKT-T0252A03REV8

TO-252 (DPAK) MOLDED, 3 LEAD, OPTION AA

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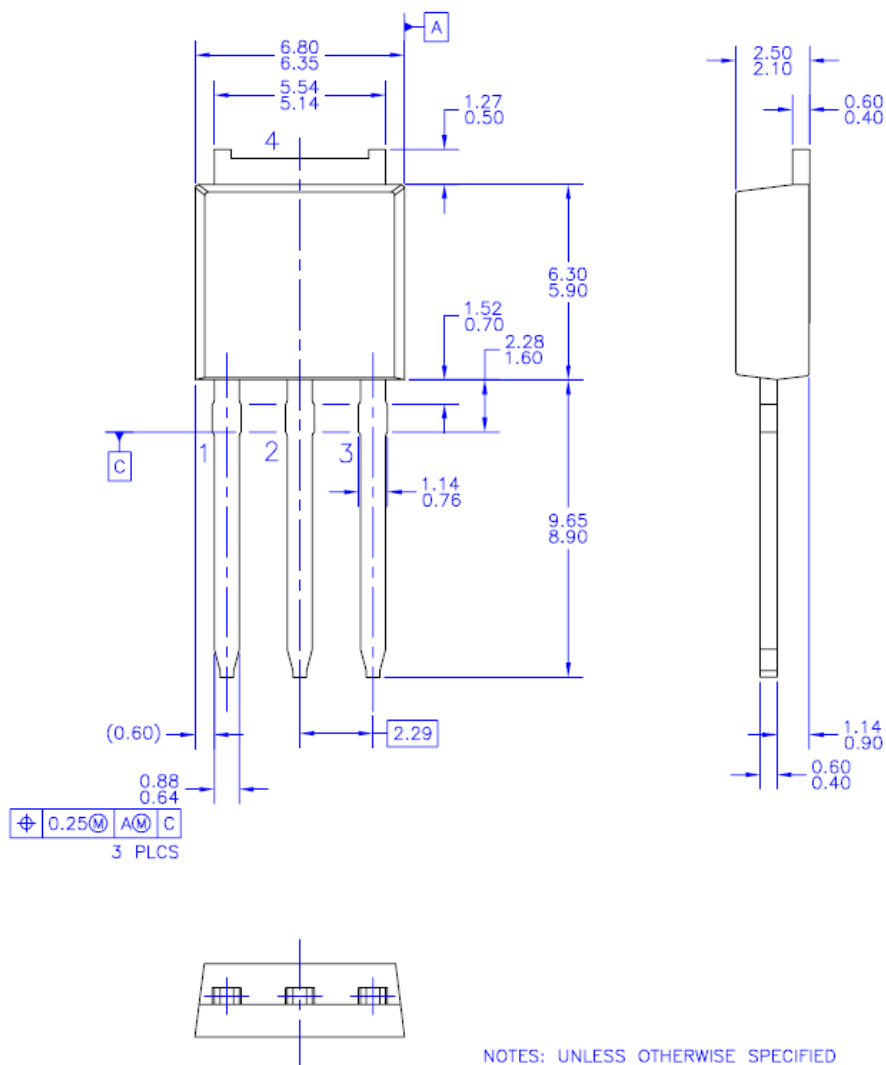
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DIMENSIONS IN MILLIMETERS

Mechanical Dimensions

I-PAK



TO-251 (IPAK) MOLDED, 3LEAD, OPTION AA

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

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Dimensions in Millimeters

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